



SOT1160-1

plastic, extremely thin quad flat package; no leads; 10 terminals; 0.4 mm pitch; 1.4 mm x 1.8 mm x 0.5 mm body

26 January 2021

Package information

1 Package summary

Terminal position code	Q (quad)
Package type descriptive code	XQFN10
Package type industry code	XQFN10
Package style descriptive code	XQFN (extremely thin quad flatpack; no leads)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	29-12-2009
Manufacturer package code	SOT1160

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	1.3	1.4	1.5	mm
package width	1.7	1.8	1.9	mm
seated height	-	-	0.5	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	10	-	



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2 Package outline

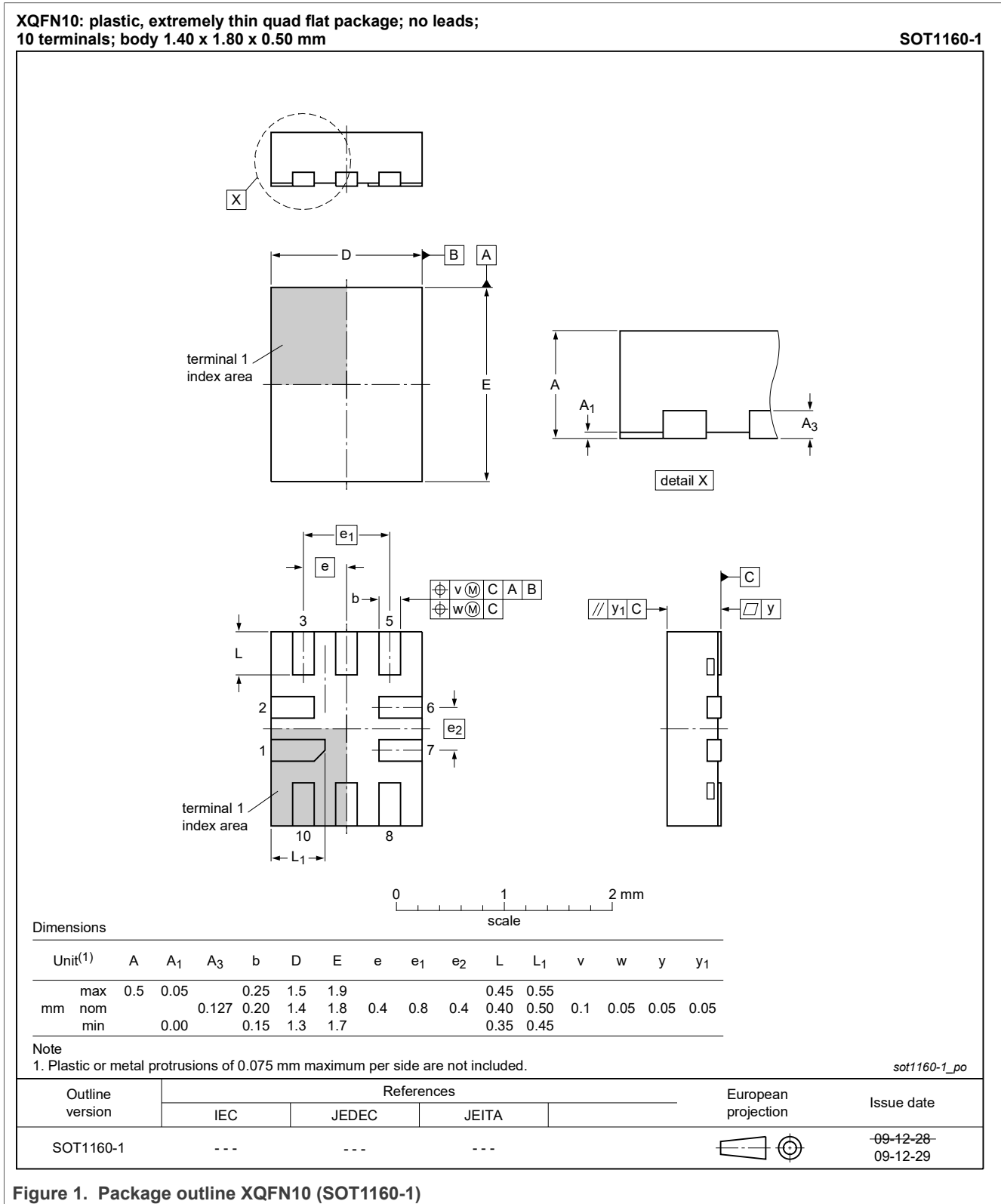


Figure 1. Package outline XQFN10 (SOT1160-1)

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3 Soldering

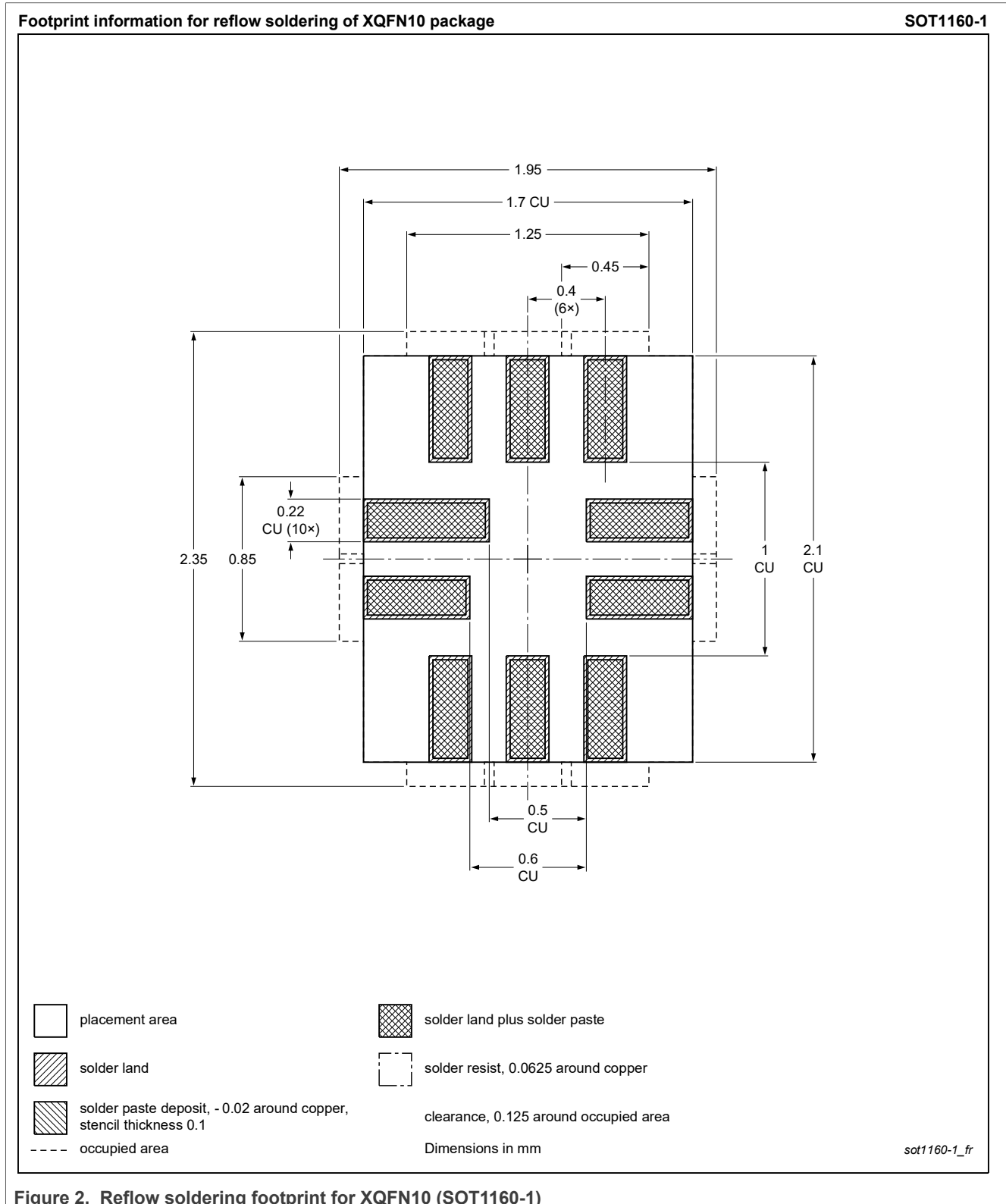


Figure 2. Reflow soldering footprint for XQFN10 (SOT1160-1)

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4 Legal information

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